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# IMPORTANT NOTICE

10 December 2015

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## 1. Global joint venture starts operations as WeEn Semiconductors

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Dear customer,

As from November 9th, 2015 NXP Semiconductors N.V. and Beijing JianGuang Asset Management Co. Ltd established Bipolar Power joint venture (JV), **WeEn Semiconductors**, which will be used in future Bipolar Power documents together with new contact details.

In this document where the previous NXP references remain, please use the new links as shown below.

**WWW** - For [www.nxp.com](http://www.nxp.com) use [www.ween-semi.com](http://www.ween-semi.com)

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If you have any questions related to this document, please contact our nearest sales office via e-mail or phone (details via [salesaddresses@ween-semi.com](mailto:salesaddresses@ween-semi.com)).

Thank you for your cooperation and understanding,

WeEn Semiconductors



# DATA SHEET

**BYV29 series**  
Rectifier diodes  
ultrafast

Product specification

September 1998



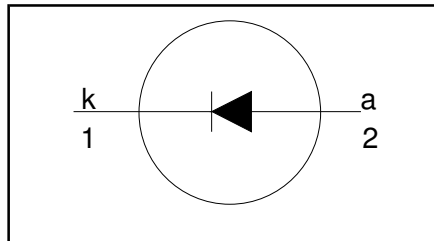
**Rectifier diodes  
ultrafast**

**BYV29 series**

**FEATURES**

- Low forward volt drop
- Fast switching
- Soft recovery characteristic
- High thermal cycling performance
- Low thermal resistance

**SYMBOL**



**QUICK REFERENCE DATA**

$V_R = 300\text{ V} / 400\text{ V} / 500\text{ V}$
$V_F \leq 1.03\text{ V}$
$I_{F(AV)} = 9\text{ A}$
$t_{rr} \leq 60\text{ ns}$

**GENERAL DESCRIPTION**

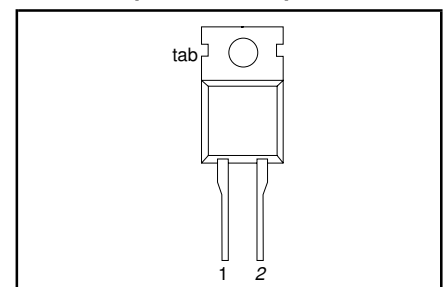
Ultra-fast, epitaxial rectifier diodes intended for use as output rectifiers in high frequency switched mode power supplies.

The BYV29 series is supplied in the conventional leaded SOD59 (TO220AC) package.

**PINNING**

PIN	DESCRIPTION
1	cathode
2	anode
tab	cathode

**SOD59 (TO220AC)**



**LIMITING VALUES**

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.			UNIT
$V_{RRM}$	Peak repetitive reverse voltage	<b>BYV29</b>	-	<b>-300</b>	<b>-400</b>	<b>-500</b>	V
$V_{RWM}$	Crest working reverse voltage		-	300	400	500	V
$V_R$	Continuous reverse voltage		-	300	400	500	V
$I_{F(AV)}$	Average forward current <sup>1</sup>	square wave; $\delta = 0.5$ ; $T_{mb} \leq 123\text{ }^\circ\text{C}$	-	9			A
$I_{FRM}$	Repetitive peak forward current	$t = 25\text{ }\mu\text{s}$ ; $\delta = 0.5$ ; $T_{mb} \leq 123\text{ }^\circ\text{C}$	-	18			A
$I_{FSM}$	Non-repetitive peak forward current.	$t = 10\text{ ms}$	-	100			A
		$t = 8.3\text{ ms}$ sinusoidal; with reapplied $V_{RRM(max)}$	-	110			A
$T_{stg}$	Storage temperature		-40	150			$^\circ\text{C}$
$T_j$	Operating junction temperature		-	150			$^\circ\text{C}$

**THERMAL RESISTANCES**

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j-mb}$	Thermal resistance junction to mounting base		-	-	2.5	K/W
$R_{th\ j-a}$	Thermal resistance junction to ambient	in free air.	-	60	-	K/W

<sup>1</sup> Neglecting switching and reverse current losses.

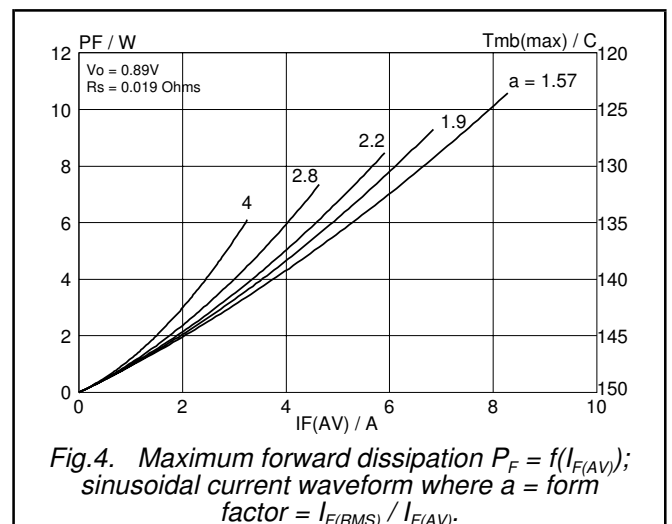
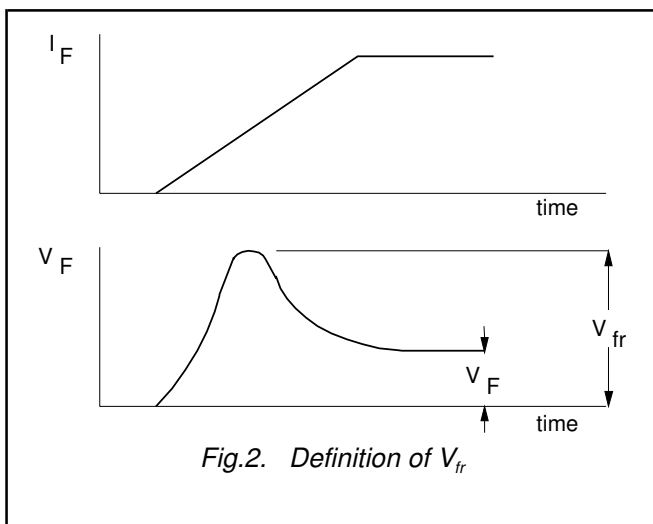
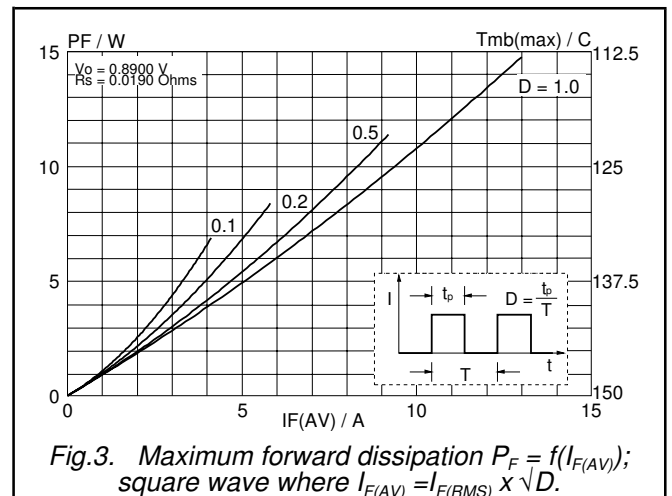
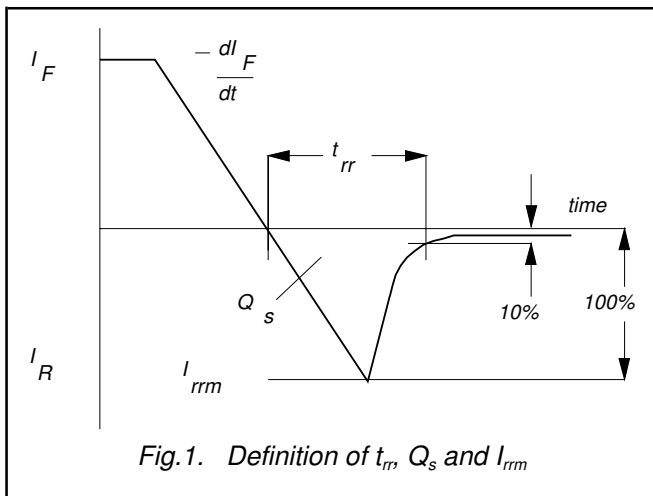
Rectifier diodes  
ultrafast

BYV29 series

**ELECTRICAL CHARACTERISTICS**

$T_j = 25\text{ }^\circ\text{C}$  unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_F$	Forward voltage	$I_F = 8\text{ A}; T_j = 150\text{ }^\circ\text{C}$	-	0.90	1.03	V
		$I_F = 8\text{ A}$	-	1.05	1.25	V
		$I_F = 20\text{ A}$	-	1.20	1.40	V
$I_R$	Reverse current	$V_R = V_{RRM}$	-	2.0	50	$\mu\text{A}$
$Q_s$	Reverse recovery charge	$V_R = V_{RRM}; T_j = 100\text{ }^\circ\text{C}$ $I_F = 2\text{ A to } V_R \geq 30\text{ V};$ $di_F/dt = 20\text{ A}/\mu\text{s}$	-	0.1	0.35	mA
$t_{rr}$	Reverse recovery time	$I_F = 1\text{ A to } V_R \geq 30\text{ V};$ $di_F/dt = 100\text{ A}/\mu\text{s}$	-	50	60	ns
$I_{rrm}$	Peak reverse recovery current	$I_F = 10\text{ A to } V_R \geq 30\text{ V};$ $di_F/dt = 50\text{ A}/\mu\text{s}; T_j = 100\text{ }^\circ\text{C}$	-	4.0	5.5	A
$V_{fr}$	Forward recovery voltage	$I_F = 10\text{ A}; di_F/dt = 10\text{ A}/\mu\text{s}$	-	2.5	-	V



Rectifier diodes  
ultrafast

BYV29 series

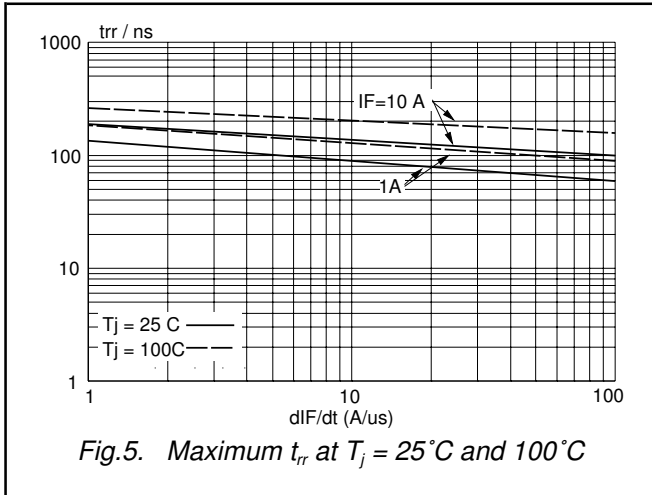


Fig.5. Maximum  $t_{rr}$  at  $T_j = 25^\circ\text{C}$  and  $100^\circ\text{C}$

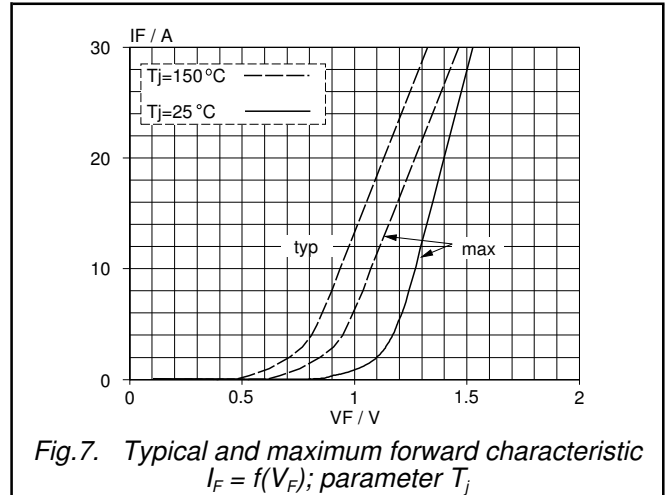


Fig.7. Typical and maximum forward characteristic  $I_F = f(V_F)$ ; parameter  $T_j$

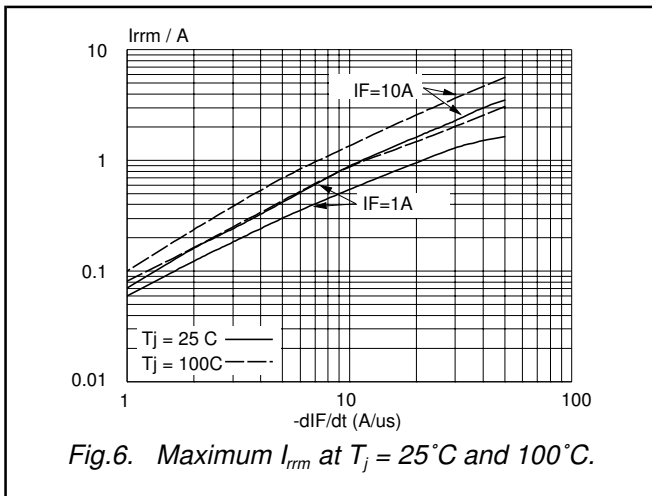


Fig.6. Maximum  $I_{rrm}$  at  $T_j = 25^\circ\text{C}$  and  $100^\circ\text{C}$ .

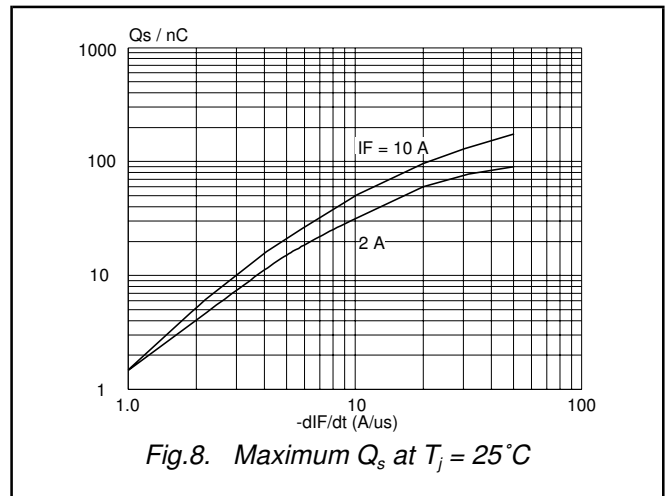


Fig.8. Maximum  $Q_s$  at  $T_j = 25^\circ\text{C}$

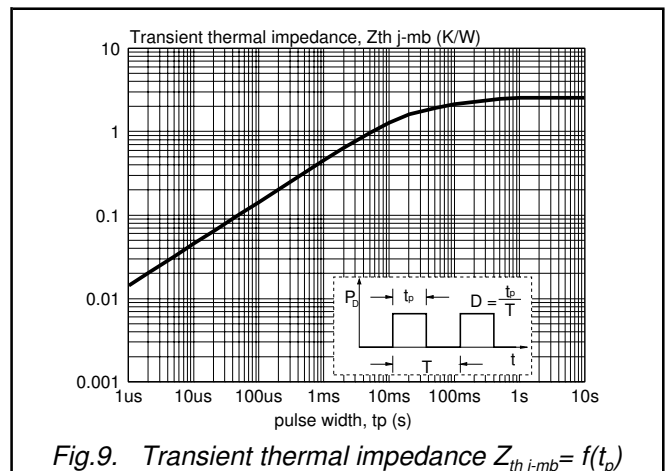
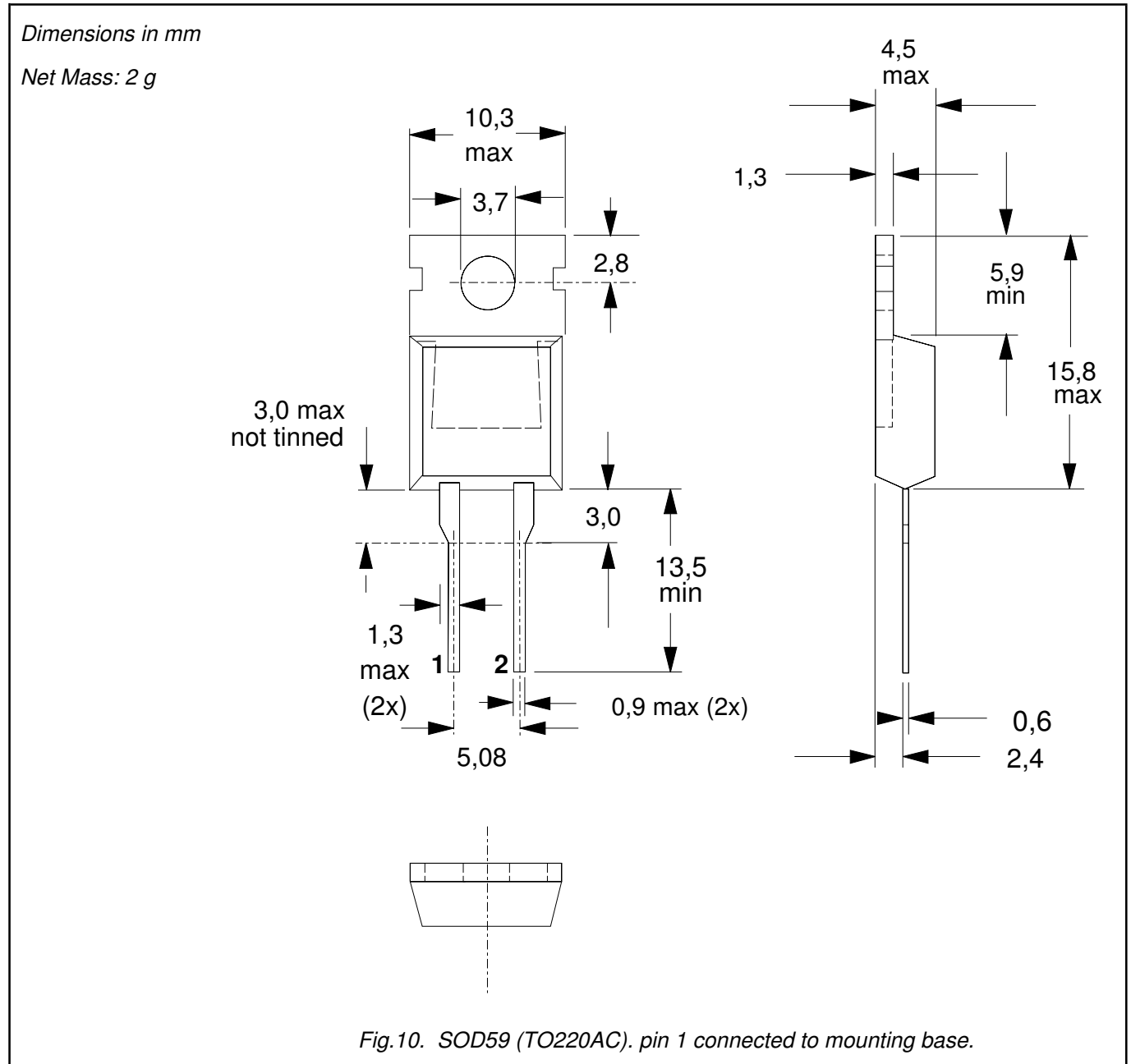


Fig.9. Transient thermal impedance  $Z_{th\ j-mb} = f(t_p)$

Rectifier diodes  
ultrafast

BYV29 series

**MECHANICAL DATA**



## Legal information

### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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### Contact information

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